

POWERED BY Dialog

Mfg. composite material - by forming body from two metal tapes with powder- storing portion between them, then filling body with powder
Patent Assignee: TANAKA DENSHI KOGYO KK

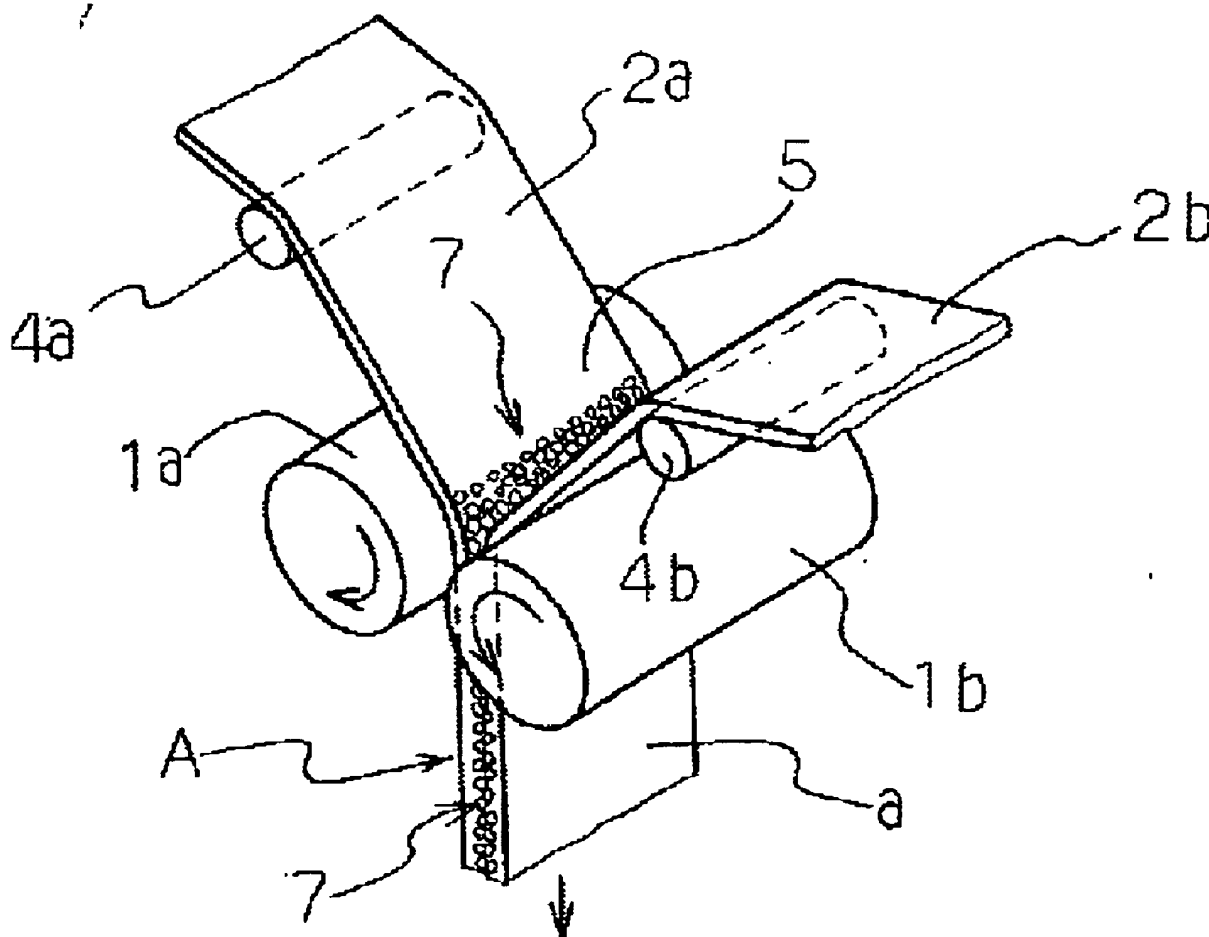
Patent Family

| Patent Number | Kind | Date | Application Number | Kind | Date | Week | Type |
|---------------|------|----------|--------------------|------|----------|--------|------|
| JP 6218580 | A | 19940809 | JP 9311685 | A | 19930127 | 199436 | B |

Priority Applications (Number Kind Date): JP 9311685 A (19930127)

Patent Details

| Patent | Kind | Language | Page | Main IPC | Filing Notes |
|------------|------|----------|------|-------------|--------------|
| JP 6218580 | A | | 7 | B23K-035/40 | |



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Solder material mfr. of various shapes - by compression moulding silver, aluminium and copper into thin sheet

Patent Assignee: MEIDENSHA CORP

Patent Family

| Patent Number | Kind | Date | Application Number | Kind | Date | Week | Type |
|---------------|------|----------|--------------------|------|----------|--------|------|
| JP 3032488 | A | 19910213 | JP 89166466 | A | 19890628 | 199113 | B |
| JP 2679268 | B2 | 19971119 | JP 89166446 | A | 19890628 | 199751 | |

Priority Applications (Number Kind Date): JP 89166446 A (19890628); JP 89166466 A (19890628)

Patent Details

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|------------|------|----------|------|-------------|----------------------------------|
| JP 3032488 | A | | 4 | | |
| JP 2679268 | B2 | | 3 | B23K-035/40 | Previous Publ. patent JP 3032488 |

Abstract:

JP 3032488 A

Process for mfg. a solder material of Ag, Al, and Cu, comprises compression moulding a powder mixt. contg. by wt., 25-80% Ag, 14-75% Al, and 1-30% Cu into a thin sheet.

Most pref., the solder material comprises by wt., 30-58% Ag, 26-60% Al, and 10-25% Cu, and the powder is classified to 100 mesh or under, with Al pref. comprising grains 20 microns or larger in dia..

USE/ADVANTAGE - Provides a thin sheet solder of desired shape (by readily machining with a C.G. a laser beam, having a low soldering temp. of ca. 650 deg.C and applicable to various materials not only Cu but also to Fe, stainless steel, Coval, Ti, Ni, etc.. (4pp Dwg.No.0/1)

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